

DESCRIPTION

The MXD100N03 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

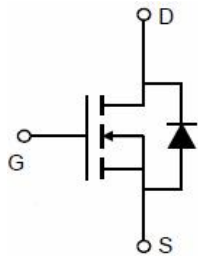
GENERAL FEATURES

- $V_{DS}=30V, I_D=100A$
 $R_{DS(ON)}(Typ.)=6.7m\Omega @ V_{GS}=4.5V$
 $R_{DS(ON)}(Typ.)=3.6m\Omega @ V_{GS}=10V$

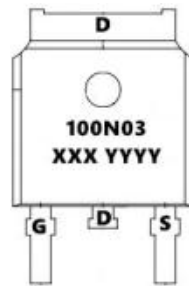
APPLICATION

- Battery protection
- Load switch
- Uninterruptible power supply

PINOUT



Schematic diagram



Marking and pin Assignment



TO-252-3L top view

ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MXD100N03	-55°C to 175°C	TO-252-3L	2500

ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous ($V_{GS}=10V, T_C=25^\circ C$)	I_D	100	A
Drain Current-Continuous ($V_{GS}=10V, T_C=100^\circ C$)	I_D	59	A
Pulsed Drain Current ^(Note1)	I_{DM}	360	A
Single Pulse Avalanche Energy ^(Note2)	E_{AS}	95	mJ
Avalanche Current	I_{AS}	19.5	A
Total Power Dissipation ^(Note4)	P_D	68	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^\circ C$
Thermal Resistance, Junction-to-Ambient (Steady State) ^(Note1)	$R_{\theta JA}$	62	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient ($t \leq 10s$) ^(Note1)	$R_{\theta JA}$	25	$^\circ C/W$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.2	$^\circ C/W$

Note 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

Note 2. The test condition is, $V_{DD} = 15V, V_G = 10V, R_G = 25\Omega, L = 0.5mH, I_{AS} = 19.5A$

Note 3. The data tested by pulsed Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$

Note 4. The power dissipation is limited by 150°C junction temperature



ELECTRICAL CHARACTERISTICS($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
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Off Characteristics

Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	30	32	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=30V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA

On Characteristics

Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.6	2.5	V
Drain-Source On-State Resistance ^(Note3)	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=20A$	-	6.7	9.5	m Ω
		$V_{GS}=10V, I_D=30A$	-	3.6	5.5	m Ω

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{DS}=15V, V_{GS}=0V, F=1.0MHz$	-	2100	-	pF
Output Capacitance	C_{oss}		-	326	-	pF
Reverse Transfer Capacitance	C_{rss}		-	282	-	pF

Switching Characteristics

Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=15V, I_D=30A, V_{GS}=10V, R_{GEN}=3\Omega$	-	21	-	nS
Turn-on Rise Time	t_r		-	32	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	59	-	nS
Turn-Off Fall Time	t_f		-	34	-	nS
Total Gate Charge	Q_g	$V_{DS}=15V, I_D=30A, V_{GS}=10V$	-	45	-	nC
Gate-Source Charge	Q_{gs}		-	3	-	nC
Gate-Drain Charge	Q_{gd}		-	15	-	nC

Drain-Source Diode Characteristics

Continuous Source Current	I_S		-	-	90	A
Pulsed Source Current	I_{SM}		-	-	360	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=30A$	-	-	1.2	V
Reverse Recovery Time	t_{rr}	$I_F=20A, di/dt=100A/\mu s$	-	15	-	ns
Reverse Recovery Charge	Q_{rr}		-	4	-	nC

Note 3. The data tested by pulsed Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1. Output Characteristics

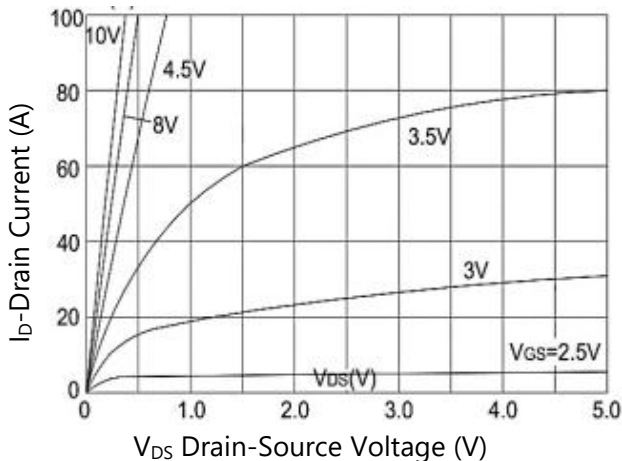


Figure 2. Typical Transfer Characteristics

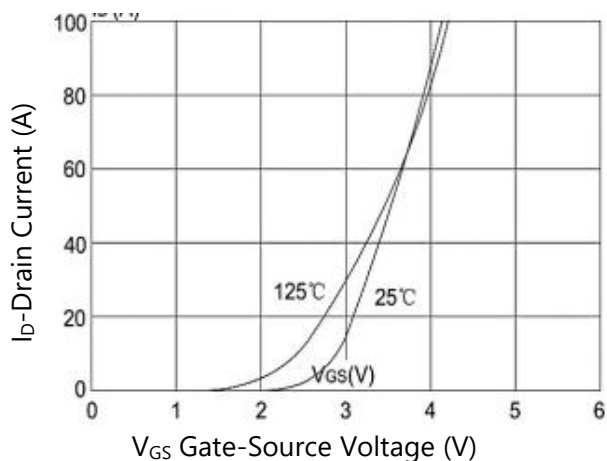


Figure 3. R_{ds(on)} vs Drain Current

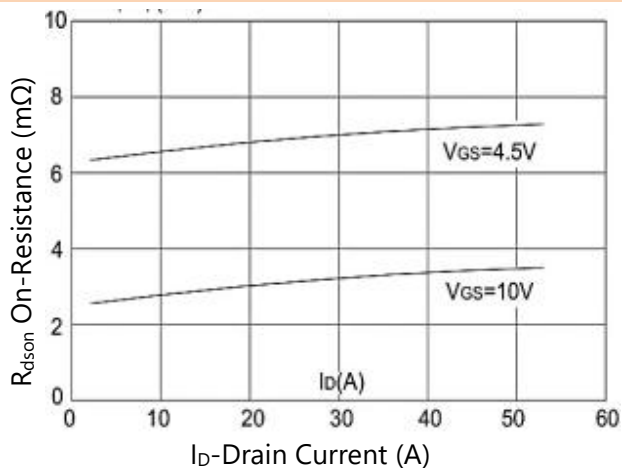


Figure 4. Body Diode Characteristics

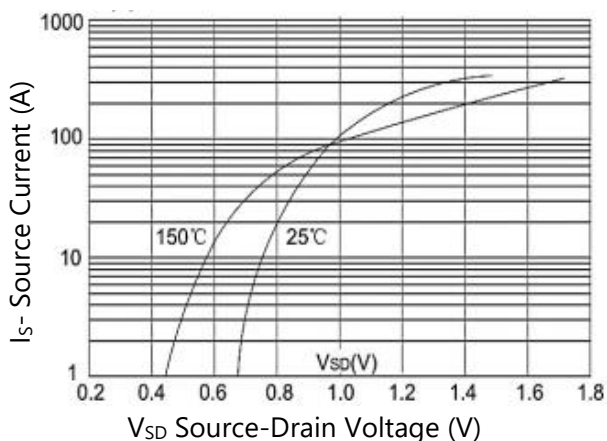


Figure 5. Gate Charge

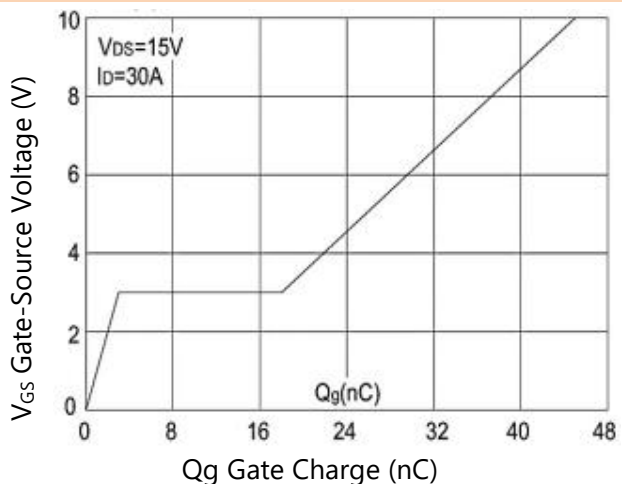
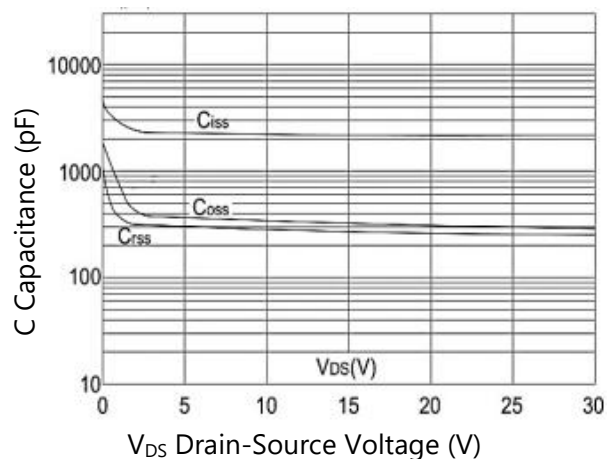


Figure 6. Capacitance Characteristics



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7. $V_{BR(DSS)}$ vs Junction Temperature

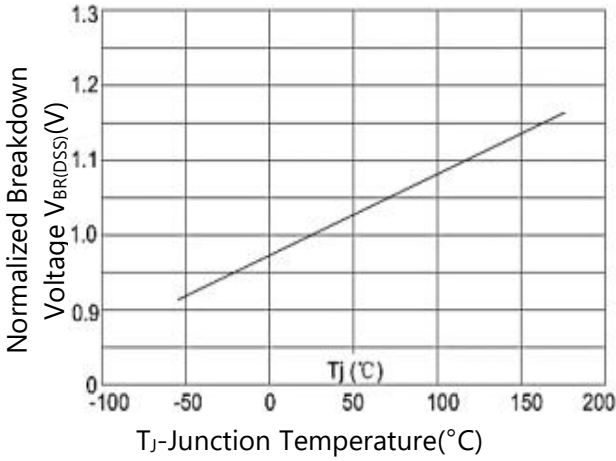


Figure 8. $R_{DS(on)}$ vs Junction Temperature

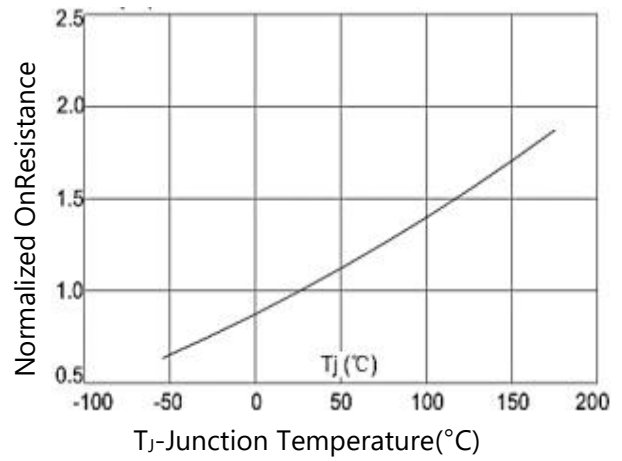


Figure 9. Maximum Continuous Drain Current

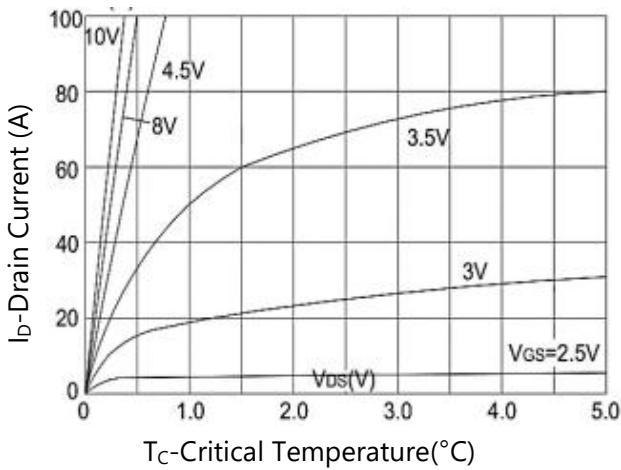


Figure 10. Safe Operation Area

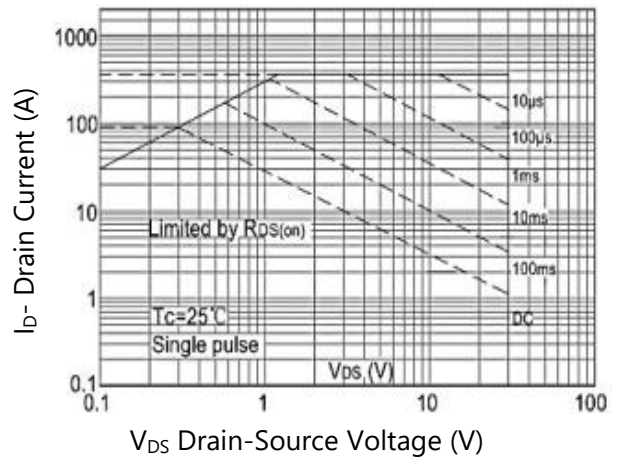
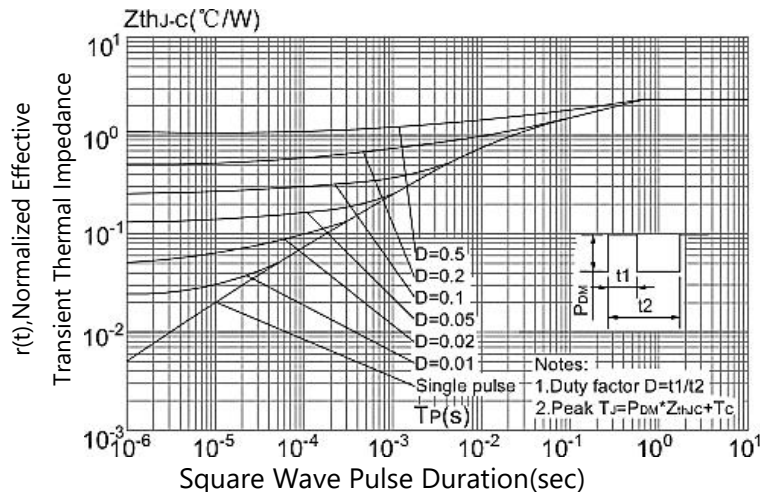
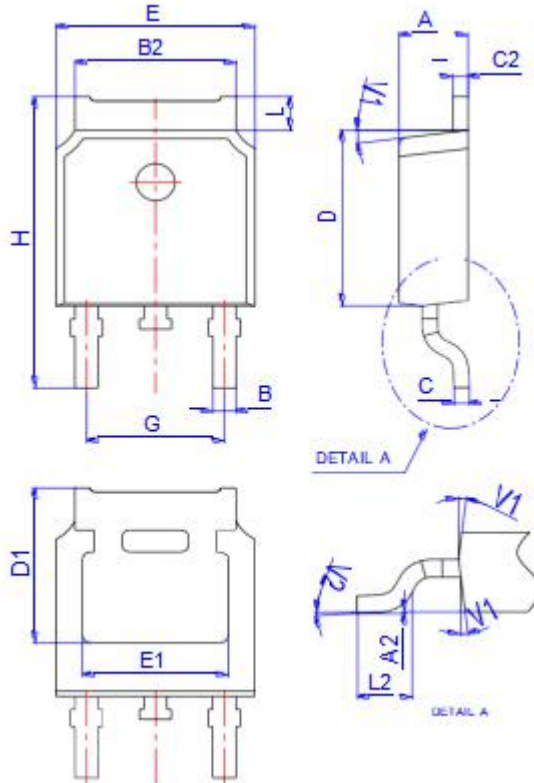


Figure 11. Normalized Maximum Transient Thermal Impedance



PACKAGE INFORMATION

TO-252-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.10	2.50	0.083	0.098
A2	0	0.10	0	0.004
B	0.66	0.86	0.026	0.034
B2	5.18	5.48	0.202	0.216
C	0.40	0.60	0.016	0.024
C2	0.44	0.58	0.017	0.023
D	5.90	6.30	0.232	0.248
D1	5.30REF		0.209REF	
E	6.40	6.80	0.252	0.268
E1	4.63	-	0.182	-
G	4.47	4.67	0.176	0.184
H	9.50	10.70	0.374	0.421
L	1.09	1.21	0.043	0.048
L2	1.35	1.65	0.053	0.065
V1	7°TYP		7°TYP	
V2	0°	6°	0°	6°